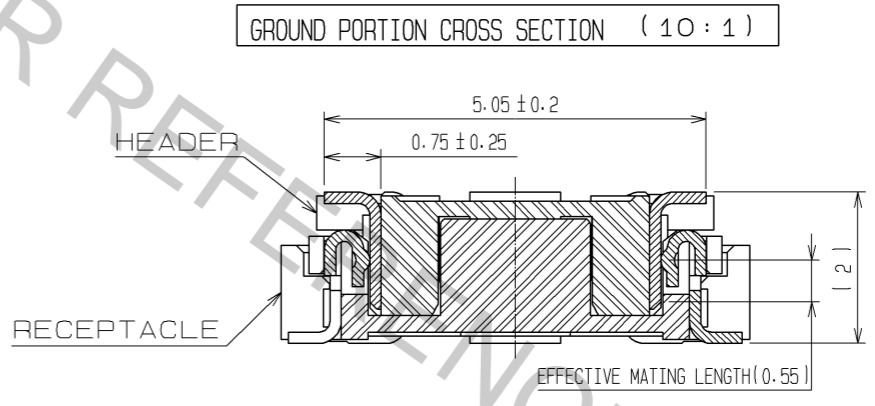
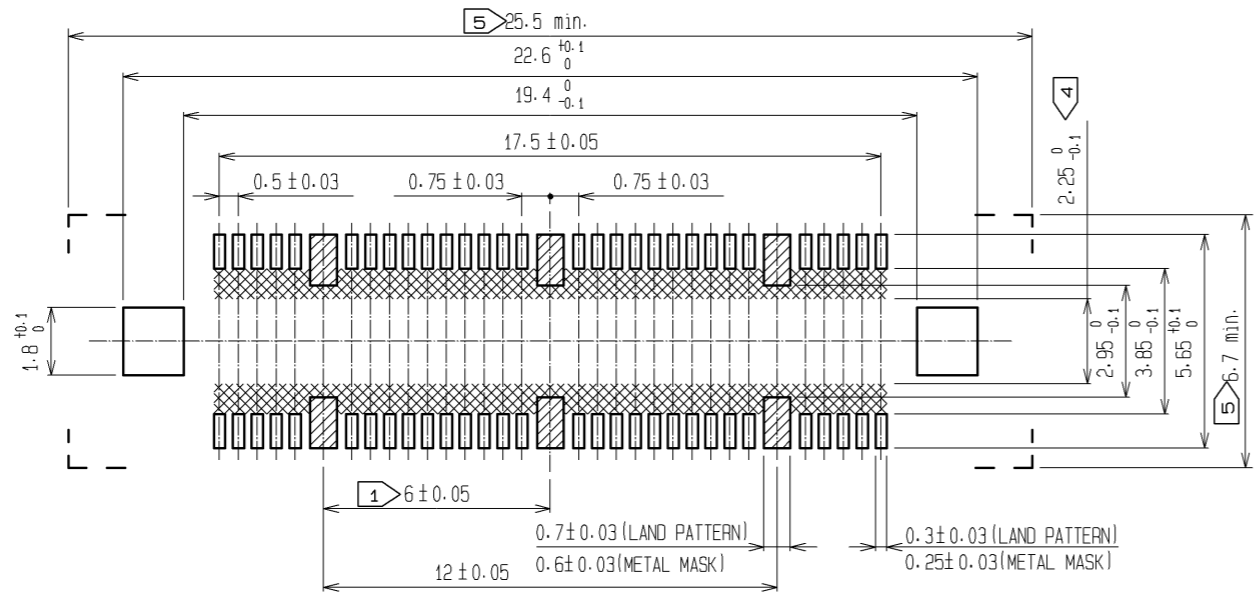


RECOMMENDED LAND PATTERN DIMENSION OF PCB



- NOTES
- ① 6 HATCHED PARTS: GROUND CIRCUIT.
 - ② SMT LEAD-COPLANARITY: 0.1 MAX.
 - ③ THIS PRODUCT HAS NO POLARITY TO PATTERN FOR MOUNTING.
 - ④ MAKE SURE WIDTH OF PATTERN IS WITHIN THAT OF LAND, OR LEAD MAY TOUCH PATTERN. (THIS APPLIES TO HATCHED AREA.)
 - ⑤ DO NOT MOUNT OTHER DEVICES ONTO [] AREA, OR MATING PAIR CANNOT BE MATED.
 - ⑥ THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

4	PHOSPHOR BRONZE	TIN PLATING	
3	PHOSPHOR BRONZE	TIN PLATING	
2	COPPER ALLOY	CONTACT AREA : GOLD 0.1μm min.	
		LEAD AREA : GOLD FLASH	
		UNDER PLATING : NICKEL 1μm min.	
NO.	MATERIAL	FINISH.	REMARKS

1	LCP	BEIGE	UL94V-0					
NO.	MATERIAL	FINISH.	REMARKS	NO.	MATERIAL	FINISH.	REMARKS	
UNITS	mm	SCALE	5 : 1	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
APPROVED : HS. OKAWA		07.07.10		DRAWING NO.		EDC3-152096-25		
CHECKED : HS. OZAWA		07.07.10		PART NO.		FX11LB-60P/6-SV(71)		
DESIGNED : SY. KAMIGA		07.07.10		CODE NO.		CL573-0012-0-71		
DRAWN : HK. SUNADORI		07.06.27						